

## CURRENT STATUS OF THE CLAIMS

### In the Claims

The following is a marked-up version of the claims with the language that is underlined (“    ”) being added and the language that contains strikethrough (“~~—~~”) being deleted:

1-7 (CANCELLED)

8. (CURRENTLY AMENDED) An electronic package comprising:  
a substrate; and  
a free-standing compliant off-chip interconnect, wherein the free-standing compliant off-chip interconnect includes a first free-standing arcuate structure that is substantially parallel to the substrate, wherein the first free-standing arcuate structure is curved in the plane substantially parallel to the substrate.

9. (CANCELLED)

10. (ORIGINAL) The electronic package of claim 8, wherein the first arcuate structure is connected to an assembly post.

Claims 11-14 (CANCELLED)

15. (ORIGINAL) The electronic package of claim 8, wherein the first arcuate structure has a thickness of about 3 to about 30 micrometers, a width of about 5 to about 50 micrometers, and a mean radius of about 5 to about 100 micrometers.

16. (CANCELLED)

17. (ORIGINAL) The electronic package of claim 8, wherein the assembly post has a height of about 5 to about 50 micrometers.

18-19 (CANCELLED)

20. (ORIGINAL) The electronic package of claim 8, wherein the substrate can be a material chosen from a semiconductor, glass, ceramic, and quartz material.

21-26. (CANCELLED)

27. (NEW) A free-standing compliant off-chip interconnect, comprising:  
a first arcuate structure;  
a second arcuate structure, wherein the first arcuate structure and the second arcuate structure are disposed in substantially parallel planes; and  
a middle post, wherein the first arcuate structure is connected to a lower portion of the middle post, and wherein the second arcuate structure is connected to an upper portion of the middle post.

28. (NEW) The compliant off-chip interconnect of claim 27, wherein the first arcuate structure has a first mean radius and the second arcuate structure has a second mean radius, wherein the first mean radius and the second mean radius are not equivalent.

29. (NEW) The compliant off-chip interconnect of claim 27 wherein the first arcuate structure has a first mean radius and the second arcuate structure has a second mean radius, wherein the first mean radius and the second mean radius are equivalent.

30. (NEW) The compliant off-chip interconnect of claim 27, wherein the first arcuate structure has a thickness of about 3 to about 30 micrometers, a width of about 5 to about 50 micrometers, and a mean radius of about 5 to about 100 micrometers.

31. (NEW) The compliant off-chip interconnect of claim 27, wherein the second arcuate structure has a thickness of about 3 to about 30 micrometers, a width of about 5 to about 50 micrometers, and a mean radius of about 5 to about 50 micrometers.
32. (NEW) The compliant off-chip interconnect of claim 27, wherein the middle post has a height of about 5 to about 50 micrometers.
33. (NEW) The compliant off-chip interconnect of claim 27, further comprising:  
a substrate upon which the first arcuate structure and the second arcuate structure are disposed.
34. (NEW) The electronic package of claim 8, wherein the free-standing compliant off-chip interconnect further includes:  
a second free-standing arcuate structure that is substantially parallel to the substrate, and wherein the first arcuate structure and the second arcuate structure are disposed in substantially parallel planes.
35. (NEW) The electronic package of claim 8, wherein the first arcuate structure is connected to an assembly post with a first bridge.
36. (NEW) The electronic package of claim 35, wherein the first bridge includes a curved portion connecting the first arcuate structure to the assembly post.
37. (NEW) The electronic package of claim 34, wherein the second arcuate structure is connected to a fabrication post with a second bridge.
38. (NEW) The electronic package of claim 37, wherein the second bridge includes a curved portion connecting the second arcuate structure to the fabrication post.

39. (NEW) The electronic package of claim 34, wherein the second arcuate structure has a thickness of about 3 to about 30 micrometers, a width of about 5 to about 50 micrometers, and a mean radius of about 5 to about 100 micrometers.
40. (NEW) The electronic package of claim 34, wherein the first arcuate structure has a first mean radius and the second arcuate structure has a second mean radius, wherein the first mean radius and the second mean radius are not equivalent.
41. The electronic package of claim 34, wherein the first arcuate structure has a first mean radius and the second arcuate structure has a second mean radius, wherein the first mean radius and the second mean radius are equivalent.